[c2]

[c3]

[c4]



Claims

- [c1] 1. A cured composition comprising a cured residue of a curable composition comprising:
 - (a) an epoxy resin and curing agent therefor, wherein said epoxy resin is essentially free of bromine atoms;
 - (b) a flame retardant additive essentially free of phenolic groups and of epoxy groups, wherein said flame retardant is a condensation product of (i) a brominated phenol or a mixture of brominated phenols with (ii) a cyanuric halide; and
 - (c) a thermoplastic resin.
 - 2. The cured composition of claim 1, wherein said flame retardant additive has a bromine content greater than 20%.
 - 3. The cured composition of claim 1, wherein said flame retardant additive is 1,3,5-tris(2,4,6-tribromophenoxy)triazine.
 - 4. The cured composition of claim 1, wherein said flame retardant additive is 2,2'-[(1-methylethylidene)bis[(2,6-dibromo-4,1-phenylene)oxy]]bis[4,6-bis [(2,4,6-tribromophenyl)oxy]-1,3,5-triazine].
- [c5] 5. The cured composition of claim 1, wherein said flame retardant additive is soluble in toluene at a concentration of greater than 15 g/100ml of toluene at a temperature of 50 $^{\circ}$ C.
- [c6] 6. The cured composition of claim 1, wherein said epoxy resin is a glycidyl ether resin or a mixture of glycidyl ether resins containing, on average, greater than 2 epoxy groups per molecule.
- [c7] 7. The cured composition of claim 1, wherein said epoxy resin is a mixture of:

 (a1) an epoxy resin containing on average less than or equal to 2 glycidyl groups per molecule; and

 (a2) an epoxy resin containing greater than 2 glycidyl groups per molecule.
- [c8] 8. The cured composition of claim 1, wherein said thermoplastic resin has a Tg greater than $120 \, ^{\circ}$ C.

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	[c9]	9. The cured composition of claim 1, wherein said thermoplastic resin has a dissipation factor of less than 0.010 measured at 1 MHz at room temperature.
Jun. 1971, Jun. 1891, 2001 Hard B B B B B B B B B B B B B B B B B B B	[c10]	10. The cured composition of claim 1, wherein said thermoplastic resin has been directly isolated from solution after polymerization.
	[c11]	11. The cured composition of claim 1, wherein said thermoplastic resin is a poly (phenylene ether).
	[c12]	12. The cured composition of claim 11, wherein said poly(phenylene ether) has a weight average molecular weight ranging from about 3,000 to 35,000 g/mol.
	[c13]	13. The cured composition of claim 11, wherein said poly(phenylene ether) has a weight average molecular weight ranging from about 3,000 to 35,000 g/mol.
Jus. 1917. 1921, 1975	[c14]	14. The cured composition of claim 11, wherein said poly(phenylene ether) has been melt processed at a temperature ranging from about 200 ° to 350 ° C.
the start cast start that the start than start the start than start.	[c15]	15. The cured composition of claim 11, wherein said poly(phenylene ether) is hydroxy functional.
	[c16]	16. The cured composition of claim 1, wherein said thermoplastic resin is one or more of a poly(phenylene ether) or a poly(styrene- co -maleic anhydride).
	[c17]	17. The cured composition of claim 1, wherein said thermoplastic resin is a reaction product of a poly(phenylene ether) and a peroxide.
	[c18]	18. The cured composition of claim 1, wherein said thermoplastic resin is a reaction product of a poly(phenylene ether), a peroxide, and a bisphenol.
	[c19]	19. The cured composition of claim 1, wherein said thermoplastic resin is a polyimide.
	[c20]	20. The cured composition of claim 1, wherein the curable composition further comprises one or more of an organic reinforcement, an inorganic reinforcement, or a filler.
	[c21]	21. The cured composition of claim 1, wherein the curable composition is essentially free of homopolymers of styrene.

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- [c22] 22. The cured composition of claim 1, wherein the epoxy resin is a multifunctional glycidyl ether.
- [c23]23. The cured composition of claim 22, wherein said multifunctional glycidyl ether is selected from the group consisting of epoxidized phenol-formaldehyde novolacs, epoxidized cresol-formaldehyde novolacs, epoxidized alkylphenolformaldehyde novolacs, epoxidized 1,1,1-tris(4-hydroxyphenyl)ethane, epoxidized 1,1,2,2-tetra(4-hydroxyphenyl) ethane, epoxidized phenoldicyclopentadiene novolacs, and epoxidized phenol-benzaldehyde novolacs.
- [c24]24. A cured composition comprising a cured residue of a curable composition comprising:
 - (a) an epoxy resin and curing agent therefor, wherein said epoxy resin is a glycidyl ether resin or mixture of glycidyl ether resins containing, on average, greater than 2 epoxy groups per molecule;
 - (b) 1,3,5-tris(2,4,6-tribromophenoxy)triazine and/or 2,2'-[(1-methylethylidene) bis[(2,6-dibromo-4,1-phenylene)oxy]]bis[4,6-bis[(2,4,6-tribromophenyl)oxy]-1,3,5-triazine]; and
 - (c) a poly(phenylene ether) resin.
- [c25]25. A cured composition comprising a cured residue of a curable composition comprising:
 - (a) an epoxidized cresol-formaldehyde novolac resin;
 - (b) 1,3,5-tris(2,4,6-tribromophenoxy)triazine; and
 - (c) a poly(phenylene ether) resin having a number average molecular weight ranging from about 1,000 to 15,000 g/mol.
- [c26]26. A laminate, comprising: a metal foil having a surface; and disposed on the surface of the metal foil, a cured residue of a curable composition comprising:
 - (a) an epoxy resin and curing agent therefor, wherein said epoxy resin is essentially free of bromine atoms;
 - (b) a flame retardant additive essentially free of phenolic groups and of epoxy groups, wherein said flame retardant is a condensation product of (i) a



brominated phenol or a mixture of brominated phenols with (ii) a cyanuric halide; and

- (c) a thermoplastic resin.
- [c27] 27. The laminate of claim 26, wherein said flame retardant additive has a bromine content greater than 20%.
- [c28] 28. The laminate of claim 26, wherein said flame retardant additive is 1,3,5-tris (2,4,6-tribromophenoxy)triazine.
- [c29] 29. The laminate of claim 26, wherein said flame retardant additive is 2,2'-[(1methylethylidene)bis[(2,6-dibromo-4,1-phenylene)oxy]]bis[4,6-bis[(2,4,6tribromophenyl)oxy]-1,3,5-triazine].
- [c30] 30. The laminate of claim 26, wherein said epoxy resin is a glycidyl ether resin or a mixture of glycidyl ether resins containing, on average, greater than 2 epoxy groups per molecule.
- [c31] 31. The laminate of claim 26, wherein said thermoplastic resin has a Tg greater than 120°C.
- [c32] 32. The laminate of claim 26, wherein said thermoplastic resin has a dissipation factor of less than 0.010 measured at 1 MHz at room temperature.
- [c33] 33. The laminate of claim 26, wherein said thermoplastic resin is a poly (phenylene ether).
- [c34] 34. The laminate of claim 33, wherein the poly(phenylene ether) has a number average molecular weight ranging from about 1,000 to 15, 000 g/mol.
- [c35] 35. The laminate of claim 33, wherein the poly(phenylene ether) has a weight average molecular weight ranging from about 3,000 to 35, 000 g/mol.
- [c36]36. The laminate of claim 26, wherein said thermoplastic resin is one or more of poly(phenylene ether) or poly(styrene- co-maleic anhydride).
- [c37]37. The laminate of claim 26, wherein said thermoplastic resin is the reaction product of a poly(phenylene ether) and a peroxide.

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[c42]

[c43]

[c44]



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[c38]	38. The laminate of claim 26, wherein said thermoplastic resin is the reaction product of a poly(phenylene ether), a peroxide, and a bisphenol.
[c39]	39. The laminate of claim 26, wherein said thermoplastic resin is a polyimide.
[c40]	40. The laminate of claim 26 wherein the curable composition further comprises one or more of an organic reinforcement, an inorganic reinforcement, or a filler.

[c41] 41. The laminate of claim 26, wherein the curable composition is essentially free of homopolymers of styrene.

> 42. The laminate of claim 26, wherein the epoxy resin is a multifunctional glycidyl ether.

43. The laminate of claim 42, wherein said multifunctional glycidyl ether is selected from the group consisting of epoxidized phenol-formaldehyde novolacs, epoxidized cresol-formaldehyde novolacs, epoxidized alkylphenolformaldehyde novolacs, epoxidized 1,1,1-tris(4-hydroxyphenyl)ethane, epoxidized 1,1,2,2-tetra(4-hydroxyphenyl) ethane, epoxidized phenoldicyclopentadiene novolacs, and epoxidized phenol-benzaldehyde novolacs.

44. A laminate, comprising: a metal foil having a surface; and disposed on the surface of the metal foil, a cured residue of a curable composition comprising:

- (a) an epoxy resin and curing agent therefor, wherein said epoxy resin is a glycidyl ether resin or mixture of glycidyl ether resins containing, on average, greater than 2 epoxy groups per molecule;
- (b) 1,3,5-tris(2,4,6-tribromophenoxy)triazine and/or 2,2'-[(1-methylethylidene) bis[(2,6-dibromo-4,1-phenylene)oxy]]bis[4,6-bis[(2,4,6-tribromophenyl)oxy]-1,3,5-triazine]; and
- (c) a poly(phenylene ether) resin.

[c45] 45. A laminate, comprising: a metal foil having a surface; and disposed on the surface of the metal foil, a cured residue of a curable



composition comprising:

- (a) an epoxidized cresol-formaldehyde novolac resin;
- (b) 1,3,5-tris(2,4,6-tribromophenoxy)triazine; and
- (c) a poly(phenylene ether) resin having a number average molecular weight ranging from about 1,000 to 15,000 g/mol.